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To the Director of the U.S. Patent and Tradema	rk Office: Please record the attached documents or the new address(es) below.
1. Name of conveying party(ies) Noriyuki Saito and Yoshinori Ito	2. Name and address of receiving party(ies) Name: Sony Corporation Internal Address:
Joint Research Agreement Government Interest Assignment Executive Order 9424, Confirmatory Lic Other Other 4. Application or patent number(s): A Patent Application No.(s) 08/30/2 05 ATRAN1	Street Address: 7-35 Kitashinagawa 6-chome Shinagawa-ku City: Tokyo 141, Japan State: 7-35 Kitashinagawa 6-chome
5. Name and address to whom correspond concerning document should be mailed: Name: Robert J. Depke Internal Address: Customer No. 33448 City: Zip:	7. Total fee (37 CFR 1.21(h) & 3.41) \$ 40.00 Authorized to be charged by credit card Authorized to be charged to deposit account Enclosed None required (government interest not affecting title) 8. Payment Information a. Credit Card Last 4 Numbers
Phone Number: Fax Number: Email Address: 9. Signature:	b. Deposit Account Number 20-1495 Authorized User Name Robert J. Depke Total number of pages including cover 3

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Mail Stop Assignment Recordation Services, Director of the USPTO, P.O.Box 1450, Alexandria, V.A. 22313-1450

PATENT

REEL: 017685 FRAME: 0474

Docket Number: <u>075834.00469</u>

ASSIGNMENT

WHEREAS, I, as a below named inventor, residing at the address stated next to my name, am a sole inventor (if only one name is listed below) or a joint inventor (if plural names are listed below) of certain new and useful improvements in

ELECTRODEPOSITION DISPLAY PANEL MANUFACTURING METHOD, ELECTRODEPOSITION DISPLAY PANEL, AND ELECTRODEPOSITION DISPLAY DEVICE

for which an application for Letters Patent of the United States of America was executed by me on the date indicated next to my name and address;

AND WHEREAS, Sony Corporation, a Japanese corporation with offices at 7-35 Kitashinagawa 6-Chome, Shinagawa-Ku, Tokyo, Japan (hereinafter referenced as ASSIGNEE) is desirous of acquiring all interest in, to and under said invention, said application disclosing the invention and in, to and under any Letters Patent or similar legal protection which may be granted therefor in the United States and in any and all foreign countries;

NOW THEREFORE, in consideration of the sum of One Dollar (\$1.00), and other good and valuable consideration, the receipt and sufficiency of which are hereby acknowledged, I, as a sole or joint inventor as indicated below, do hereby assign, sell and transfer unto the said ASSIGNEE, its successors, assigns, the entire right, title and interest in the said invention, said application, including any divisions and continuations as well as any reissues and reexaminations thereof, and in and to any and all Letters Patent of the United States, and countries foreign thereto, which may be granted for said invention, and in and to any and all priority rights and/or convention rights under the International Convention for the Protection of Industrial Property, Inter-American Convention Relating to Patents, Designs and Industrial Models, and any other international agreements to which the United States of America adheres, and to any other benefits accruing or to accrue to me with respect to the filing of applications for patents or securing of patents in the United States and countries foreign thereto, and I hereby authorize and request the Commissioner of Patents to issue the said United States Letters Patent to said ASSIGNEE, as the assignee of the whole right, title and interest thereto;

And I further agree to execute all necessary or desirable and lawful future documents, including assignments in favor of ASSIGNEE or its designee, as ASSIGNEE or its successors, assigns may from time-to-time present to me and without further remuneration, in order to perfect title in said invention, modifications, and improvements in said invention, applications and Letters Patent of the United States and countries foreign thereto;

And I further agree to properly execute and deliver and without further remuneration, such necessary or desirable and lawful papers for application for foreign patents, for filing subdivisions of said application for patent, and or, for obtaining any reissue or reissues of any Letters Patent which may be granted for my aforesaid invention, as the ASSIGNEE thereof shall hereafter require and prepare at its own expense;

And I further agree that ASSIGNEE will, upon its request, be provided promptly with all pertinent facts and documents relating to said application, said invention and said Letters Patent and legal equivalents in foreign countries as may be known and accessible to me and will testify as to the same in any interference or litigation related thereto;

And I hereby covenant that no assignment, sale, agreement or encumbrance has been or will be made or entered into which would conflict with this assignment and sale.

And I hereby authorize and request my attorney(s) of record in this application to insert the serial number and filing date of this application in the spaces that follow:

	International Application No.	PCT/JP2004/002299	International Filing Date: February 26, 2004
	This assignment executed on the c	dates indicated below.	·
Noriyuki SAITO)		
Name of first or	sole inventor		Execution date of U.S. Patent Application
Kanagawa, JAPA			
Residence of firs	t or sole inventor		
	Noringuki	Saito	28/7/05
of Firs	t or sole inventor		Date of this Assignment

PATENT REEL: 017685 FRAME: 0475

Yoshinori ITO	
Name of second inventor ,	Execution date of U.S. Patent Application
Tokyo, JAPAN	
Residence of second inventor	
Yoshinori Co	02/08/2005
Signature of second inventor	Date of this Assignment
Name of third inventor	Execution date of U.S. Patent Application
Residence of third inventor	
Signature of third inventor	Date of this Assignment
Name of fourth inventor	Execution date of U.S. Patent Application
Residence of fourth inventor	
Signature of fourth inventor	Date of this Assignment
Name of fifth inventor	Execution date of U.S. Patent Application
Residence of fifth inventor	
Signature of fifth inventor	Date of this Assignment
Name of sixth inventor	Execution date of U.S. Patent Application
Residence of sixth inventor	
Signature of sixth inventor	Date of this Assignment
Name of seventh inventor	Execution date of U.S. Patent Application
Residence of seventh inventor	
re of seventh inventor	Date of this Assignment

PATENT REEL: 017685 FRAME: 0476

RECORDED: 08/23/2005